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United States Design Patent

Harnden et al.

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- (54) PORTION OF A MATRIX FOR SURFACE MOUNT PACKAGE LEADFRAME
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- (73) Assignee: GEM Services, Inc., San Jose, CA (US)
- (*) Notice: This patent is subject to a terminal disclaimer.
- (**) Term: 14 Years
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- (52) U.S. Cl. D13/182
- (58) Field of Search D13/182; 29/622, 29/827; 174/52.2, 52.4; 206/713, 714, 715, 716, 727, 728; 257/667, 668; 333/185; 428/573

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(57) CLAIM

The ornamental design for portion of a matrix for surface mount package leadframe, as shown and described.

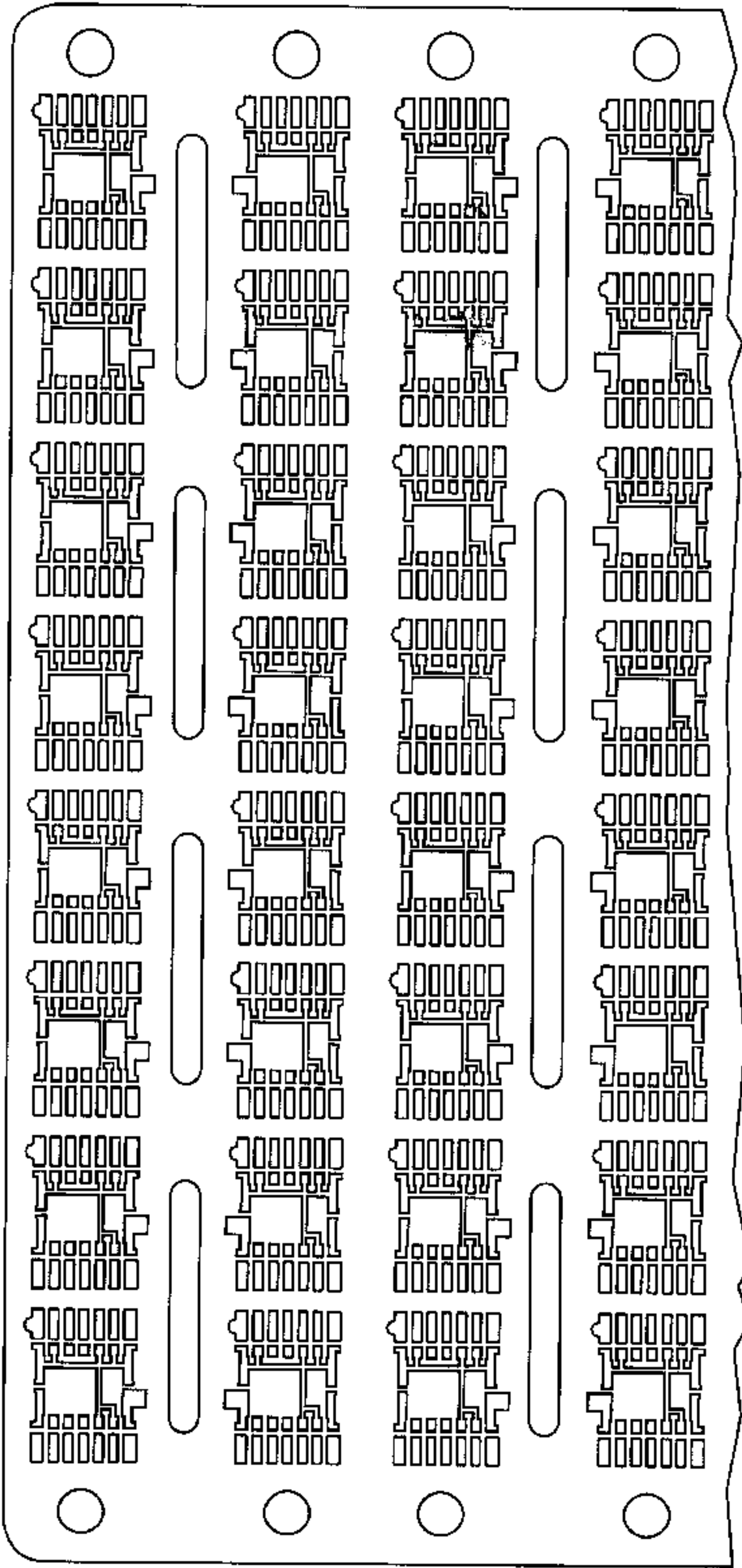
DESCRIPTION

FIG. 1 is a top plan view of a portion of a matrix incorporating a plurality of surface mount package leadframes showing my new design;

FIG. 2 is a top plan view of an enlarged fragment of the portion of a matrix for surface mount package leadframe; and,

FIG. 3 is a perspective view of a matrix incorporating a plurality of surface mount package leadframes showing my new design.

1 Claim, 3 Drawing Sheets



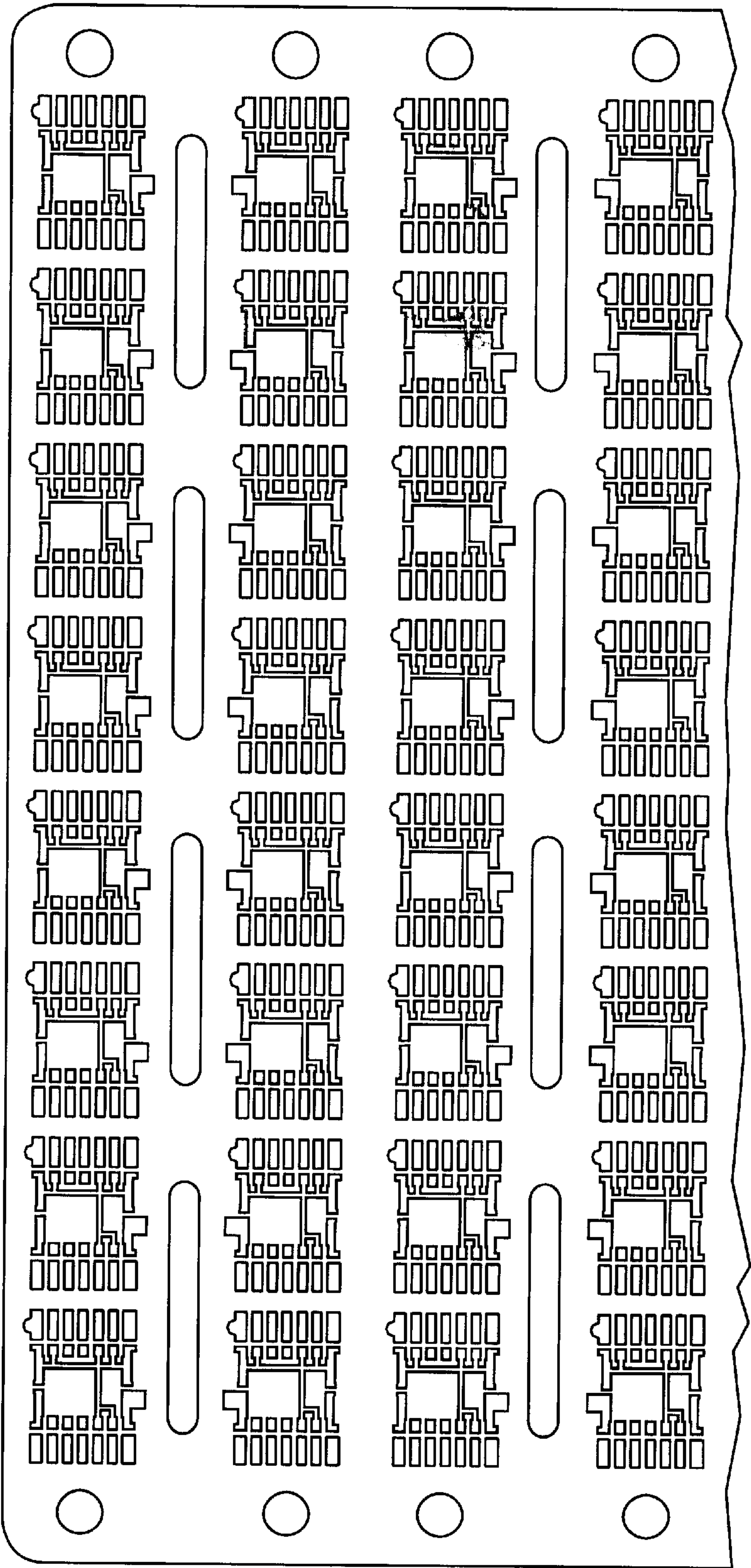


FIG. 1

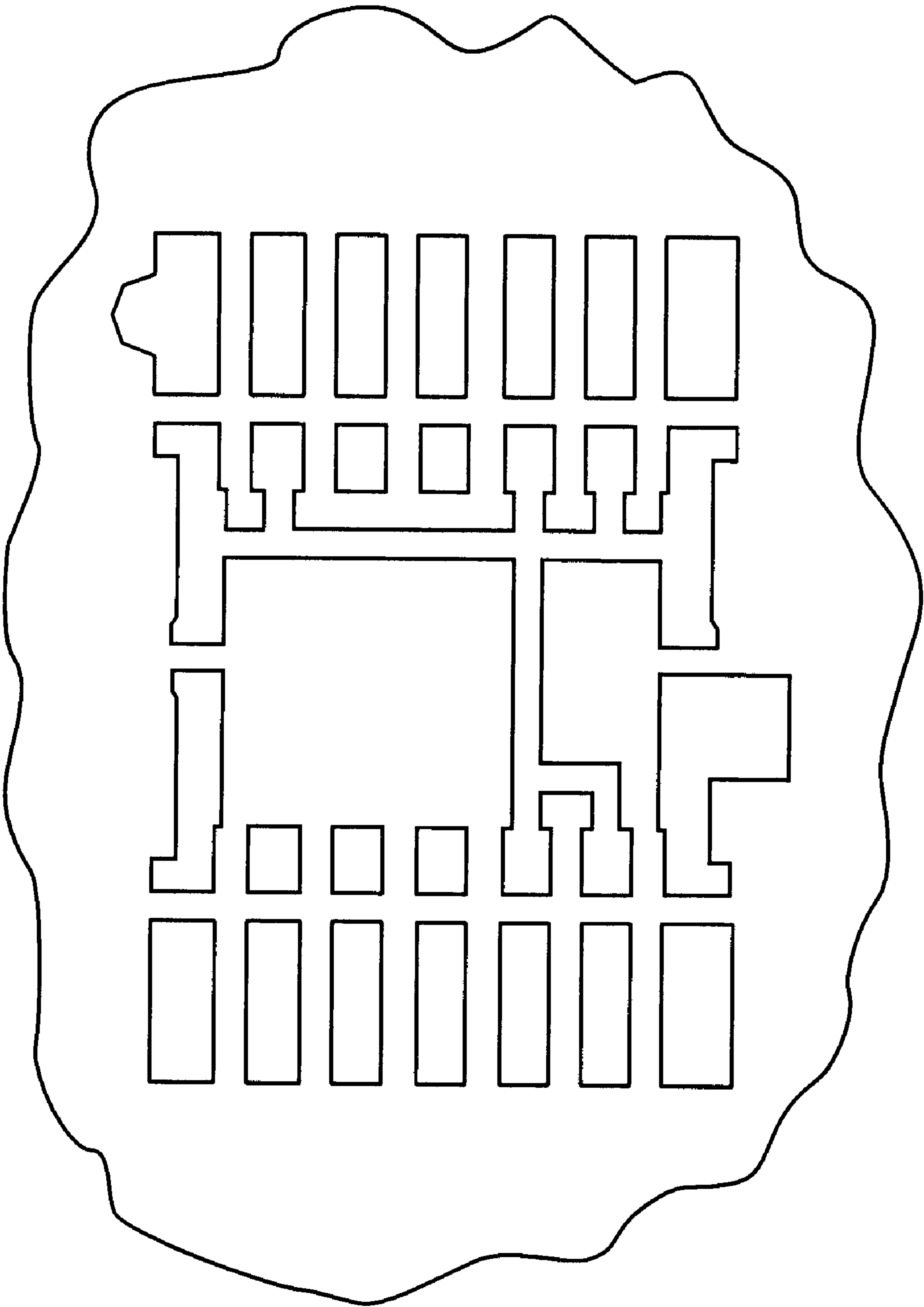


FIG. 2

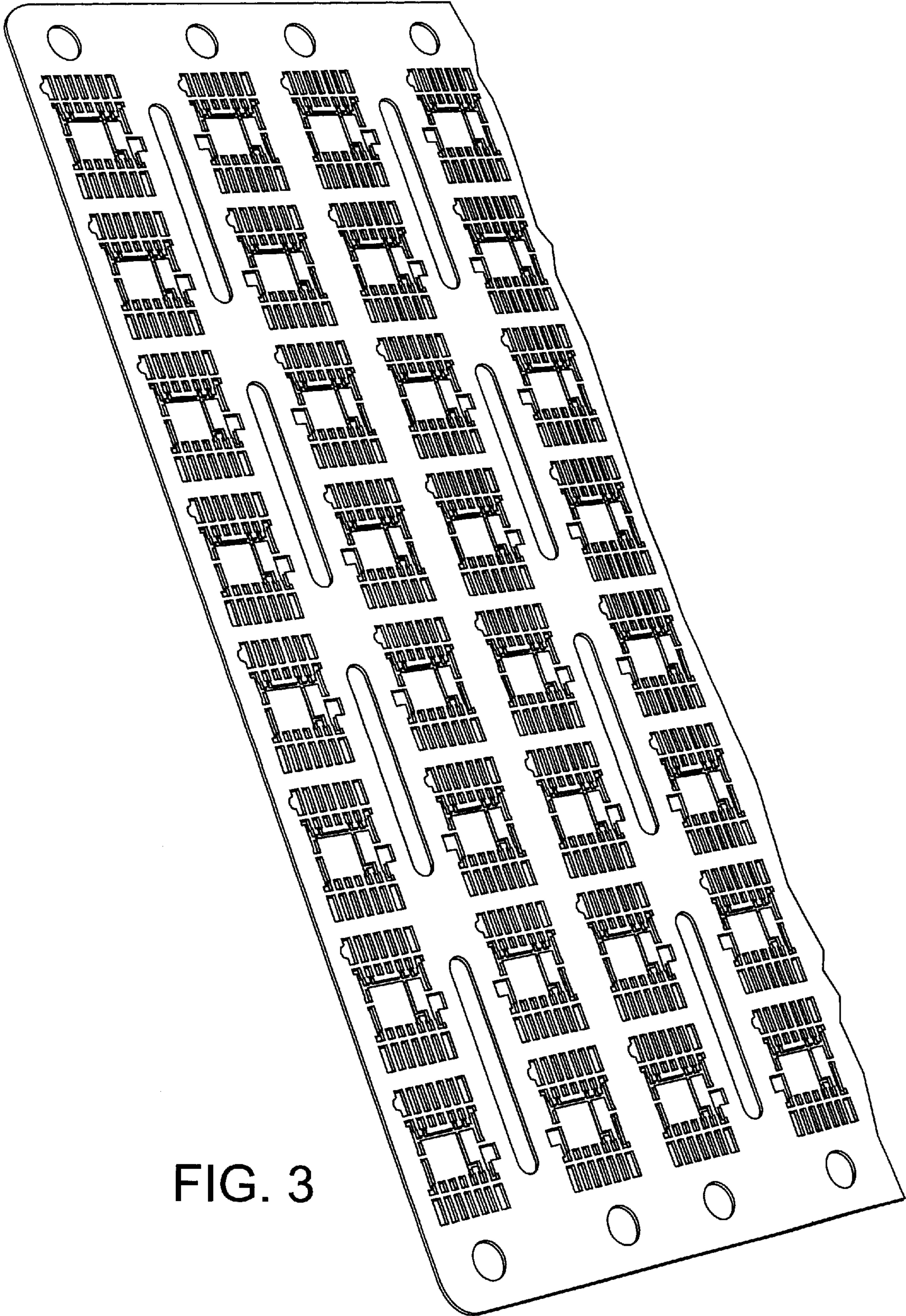


FIG. 3